



## Material Content Data Sheet



<b>Sales Product Name</b>		ICE1PCS02		<b>Issued</b>		1. August 2018		
<b>MA#</b>		MA001067378						
<b>Package</b>		PG-DIP-8-12		<b>Weight*</b>		546.32 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.922	0.90	0.90	9009	9009
leadframe	inorganic material	phosphorus	7723-14-0	0.050	0.01		91	
	non noble metal	zinc	7440-66-6	0.198	0.04		363	
	non noble metal	iron	7439-89-6	3.961	0.73		7251	
wire	non noble metal	copper	7440-50-8	160.843	29.44	30.22	294411	302116
	noble metal	gold	7440-57-5	0.157	0.03	0.03	287	287
	encapsulation	organic material	carbon black	1333-86-4	1.099	0.20		2011
encapsulation	plastics	epoxy resin	-	35.529	6.50		65033	
	inorganic material	silicondioxide	60676-86-0	329.649	60.35	67.05	603398	670442
leadfinish	non noble metal	tin	7440-31-5	7.496	1.37	1.37	13721	13721
plating	noble metal	silver	7440-22-4	0.407	0.07	0.07	746	746
glue	plastics	acrylic resin	-	0.402	0.07		736	
	noble metal	silver	7440-22-4	1.608	0.29	0.36	2943	3679
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com